

# JMF608/JMF609

## NAND Flash Support List

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## Revision History

Revision	Effect Date	Description of Revision		Author
		Reference	Description of the Change	
0.1	2013-10-15	--	Initial release.	Bow Lin
0.2	2013-12-11	3.1	Support more MLC NAND Flash	Bow Lin
0.3	2014-03-04	3.1	Support Intel L84C NAND Flash	Bow Lin
0.4	2014-03-11	3.1	Add Micron L84C and Intel L85A NAND Flash	Bow Lin
0.5	2014-05-05	3.1 3.2 3.3	Support 1) TSB 19nm C multi-LUN NAND Flash 2) TSB 1Ynm A19 (Toggle 1.0_TSOP) 3) TSB 24nm SLC (Legacy_TSOP) 4) Intel/Micron 20nm L85C	Bow Lin
0.6	2014-05-08	3.1 3.2 3.3	Support Intel 25nm MLC L74A	Bow Lin
0.7	2014-06-12	3.1 3.2 3.3	Support 1) TSB 19nm B multi-LUN NAND Flash 2) TSB 1Ynm A19 (Toggle 2.0_BGA) 3) TSB 24nm SLC (Toggle 2.0_BGA) 4) Micron 25nm MLC L74A 5) 256GB large capacity by L85A, L85C and TSB multi-LUN NAND Flash Delete 1) Intel/Micron multi-LUN NAND Flash	Bow Lin
0.8	2014-08-12	3.1 3.2 3.3	Support 1) Intel 25nm MLC L74A multi-LUN NAND Flash (page 19) 2) Intel 25nm SLC L74A NAND Flash (page 20) 3) Micron 20nm L85A multi-LUN NAND Flash (page 26) 4) Micron 25nm MLC L74A NAND Flash (page 29, 30) 5) Micron 20nm MLC L83A NAND Flash (page 31, 32) 6) Micron 20nm SLC M84A NAND Flash (page 33)	Bow Lin
0.9	2014-08-14	3.1	Delete 1) TSB 24nm SLC 128GB_4CH/4CE (page 9, 10) Modify 1) Typo error of BIN name (page 10)	Bow Lin

This document is valid until ☐ the date yyyy-mm-dd ☒ the next revision has been effective.

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## 1 Introduction

JMF608/JMF609 is a single chip SATA III NAND flash controller. For JMF608, it supports up to 4 channels with 4 CE/channel NAND flash memory. For JMF609, it supports up to 2 channels with 4 CE/channel NAND flash memory. JMF608/JMF609 provides on-chip RAM buffer, optimized for capacity below 128GB, and is suitable to cost effective, small capacity SSD or hard drive cache application. The embedded hardwired logic provides the maximum 300Mbps data read and 200Mbps data write speed to NAND flash memory.

JMF608/JMF609 has the best supporting to the latest NAND flash memory, including Toshiba 19nm and Micron 20nm Flash. It also provides the hardwired Error Correction Code (ECC) engine (up to 40b/1KB), wear leveling, and bad block management technology in this chip.

JMF608/JMF609 provides embedded processor, internal masked ROM, data SRAM, SATA link/transport layer, SATA PHY. It supports online firmware upgrade through SATA port. Data swap between different interfaces can be done very efficiency by DMA without CPU intervention.

## 2 Features

### 2.1 Flash Features

- For JMF608, support 4 hardware channels with 4 CE pins per channel to NAND flash memory.
- For JMF609, support 2 hardware channels with 4 CE pins per channel to NAND flash memory.
- On-chip data buffer RAM.
- Support Toshiba 24nm/19nm MLC and Micron 25nm/20nm MLC NAND flash memory.
- Support Legacy/Toggle 1.0/2.0/ONFI 2.3/3.0 NAND flash memory.
- Support up to 300Mbps burst read and 200Mbps burst write to NAND flash memory.
- Enhanced endurance by dynamic/static wear-leveling.
- Supports 8K/16K bytes page size.
- Supports 8/16/24/40-bit per 1KB BCH ECC.
- Support Shift-Read Feature of NAND flash memory.

### 3 NAND Flash Support List

#### 3.1 Toshiba NAND Flash

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	4Gx8bit	TC58TEG5DCJTA00 (CEx1) TC58TEG5DCJTAI0 (CEx1)	16K/19nm Type B/ Legacy to Toggle 1.0	4GB	(1CH/1CE) DCACCAAA.bin	1
					8GB	(2CH/1CE) DCACCABA.bin	2
					12GB	(3CH/1CE) DCACCACA.bin	3
					16GB	(4CH/1CE) DCACCADA.bin	4
					32GB	(4CH/2CE) DCACCAHA.bin	8
		8Gx8bit	TC58TEG6DCJTA00 (CEx1) TC58TEG6DCJTAI0 (CEx1)	16K/19nm Type B/ Legacy to Toggle 1.0	8GB	(1CH/1CE) DCBCCAAA.bin	1
					16GB	(2CH/1CE) DCBCCABA.bin	2
					24GB	(3CH/1CE) DCBCCACA.bin	3
					32GB	(4CH/1CE) DCBCCADA.bin	4
					64GB	(4CH/2CE) DCBCCAHA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b><u>Toshiba</u></b>	<b>MLC</b>	16Gx8bit	TH58TEG7DCJTA20 (CEx2) TH58TEG7DCJTAK0 (CEx2)	16K/19nm Type B/ Legacy to Toggle 1.0	16GB	(1CH/2CE) DCBCCAEA.bin	1
					32GB	(2CH/2CE) DCBCCAFA.bin	2
					64GB	(4CH/2CE) DCBCCAHA.bin	4
					128GB	(4CH/4CE) DCBCCAPA.bin	8
		32Gx8bit	TH58TEG8DCJTA20 (CEx2) TH58TEG8DCJTAK0 (CEx2)	16K/19nm Type B/ Legacy to Toggle 1.0 (multi-LUN)	32GB	(1CH/2CE) DCBCCCEA.bin	1
					64GB	(2CH/2CE) DCBCCCFA.bin	2
					128GB	(4CH/2CE) DCBCCCHA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	16Gx8bit	TH58TEG7DCJBA4C (CEx2) TH58TEG7DCJBAMC (CEx2)	16K/19nm Type B/ Toggle 2.0	16GB	(2CH/1CE) FCBCCABA.bin	1
					32GB	(4CH/1CE) FCBCCADA.bin	2
					64GB	(4CH/2CE) FCBCCAHA.bin	4
					128GB	(4CH/4CE) FCBCCAPA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	8Gx8bit	TC58TEG6DDJTA00 (CEx1) TC58TEG6DDJTAI0 (CEx1)	16K/19nm Type C/ Legacy To Toggle 1.0	8GB	(1CH/1CE) DBBCCAAA.bin	1
					16GB	(2CH/1CE) DBBCCABA.bin	2
					24GB	(3CH/1CE) DBBCCACA.bin	3
					32GB	(4CH/1CE) DBBCCADA.bin	4
					64GB	(4CH/2CE) DBBCCAHA.bin	8
		16Gx8bit	TH58TEG7DDJTA20 (CEx2) TH58TEG7DDJTAK0 (CEx2)	16K/19nm Type C/ Legacy To Toggle 1.0	16GB	(1CH/2CE) DBBCCAEA.bin	1
					32GB	(2CH/2CE) DBBCCAFa.bin	2
					64GB	(4CH/2CE) DBBCCAHA.bin	4
					128GB	(4CH/4CE) DBBCCAPA.bin	8
		32Gx8bit	TH58TEG8DDJTA20 (CEx2) TH58TEG8DDJTAK0 (CEx2)	16K/19nm Type C/ Legacy To Toggle 1.0 (multi-LUN)	32GB	(1CH/2CE) DBBCCCEA.bin	1
					64GB	(2CH/2CE) DBBCCCFA.bin	2
					128GB	(4CH/2CE) DBBCCCCHA.bin	4
					256GB	(4CH/4CE) DBBCCCFA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	16Gx8bit	TH58TEG7DDJBA4C (CEx2) TH58TEG7DDJBAMC (CEx2)	16K/19nm Type C/ Toggle 2.0	16GB	(2CH/1CE) FBBCCABA.bin	1
					32GB	(4CH/1CE) FBBCCADA.bin	2
					64GB	(4CH/2CE) FBBCCAHA.bin	4
					128GB	(4CH/4CE) FBBCCAPA.bin	8
		32Gx8bit	TH58TEG8DDJBA8C (CEx4) TH58TEG8DDJBASC (CEx4)	16K/19nm Type C/ Toggle 2.0	32GB	(2CH/2CE) FBBCCAFA.bin	1
					64GB	(4CH/2CE) FBBCCAHA.bin	2
					128GB	(4CH/4CE) FBBCCAPA.bin	4
		64Gx8bit	TH58TEG9DDJBA89 (CEx4) TH58TEG9DDJBAS9 (CEx4)	16K/19nm Type C/ Toggle 2.0 (multi-LUN)	64GB	(2CH/2CE) FBBCCCFA.bin	1
					128GB	(4CH/2CE) FBBCCCHA.bin	2
					256GB	(4CH/4CE) FBBCCCPA.bin	4

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	8Gx8bit	TC58TEG6DDKTA00 (CEx1) TC58TEG6DDKTAI0 (CEx1)	16K/1Ynm A19/ Legacy To Toggle 1.0	(1CH/1CE) DFBCCAAA.bin	1
					(2CH/1CE) DFBCCABA.bin	2
					(3CH/1CE) DFBCCACA.bin	3
					(4CH/1CE) DFBCCADA.bin	4
					(4CH/2CE) DFBCCAHA.bin	8
	16Gx8bit		TH58TEG7DDKTA20 (CEx2) TH58TEG7DDKTAK0 (CEx2)	16K/1Ynm A19/ Legacy To Toggle 1.0	(1CH/2CE) DFBCCAEA.bin	1
					(4CH/1CE) DFBCCAFa.bin	2
					(4CH/2CE) DFBCCAHA.bin	4
					(4CH/4CE) DFBCCAPA.bin	8
	32Gx8bit		TH58TEG8DDKTA20 (CEx2) TH58TEG8DDKTAK0 (CEx2)	16K/1Ynm A19/ Legacy To Toggle 1.0 (multi-LUN)	(1CH/2CE) DFBCCCEA.bin	1
					(2CH/2CE) DFBCCCFA.bin	2
					(4CH/2CE) DFBCCCHA.bin	4
					(4CH/4CE) DFBCCCPA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>MLC</b>	16Gx8bit	TH58TEG7DDKBA4C (CEx2)	16K/1Ynm A19/ Toggle 2.0	16GB	(2CH/1CE) FFBCCABA.bin	1
					32GB	(4CH/1CE) FFBCCADA.bin	2
					64GB	(4CH/2CE) FFBCCAHA.bin	4
					128GB	(4CH/4CE) FFBCCAPA.bin	8
		32Gx8bit	TH58TEG8DDKBA8C (CEx4)	16K/1Ynm A19/ Toggle 2.0	32GB	(2CH/2CE) FFBCCAFA.bin	1
					64GB	(4CH/2CE) FFBCCAHA.bin	2
					128GB	(4CH/4CE) FFBCCAPA.bin	4
		64Gx8bit	TH58TEG9DDKBA8H (CEx4)	16K/1Ynm A19/ Toggle 2.0 (multi-LUN)	64GB	(2CH/2CE) FFBCCCFA.bin	1
					128GB	(4CH/2CE) FFBCCCHA.bin	2
					256GB	(4CH/4CE) FFBCCCPA.bin	4

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>SLC</b>	4Gx8bit	8K/24nm/ Legacy	4GB	(1CH/1CE) ABCBBAAB.bin	1
				8GB	(2CH/1CE) ABCBBAAB.bin	2
				12GB	(3CH/1CE) ABCBBAAB.bin	3
				16GB	(4CH/1CE) ABCBBAAB.bin	4
				32GB	(4CH/2CE) ABCBBAAB.bin	8
		8Gx8bit	8K/24nm/ Legacy	8GB	(1CH/2CE) AGCBBAEA.bin	1
				16GB	(2CH/2CE) AGCBBAFA.bin	2
				32GB	(4CH/2CE) AGCBBAHA.bin	4
				64GB	(4CH/4CE) AGCBBAHA.bin	8
		16Gx8bit	8K/24nm/ Legacy (multi-LUN)	16GB	(1CH/2CE) AGCBBCFA.bin	1
				32GB	(2CH/2CE) AGCBBCFA.bin	2
				64GB	(4CH/2CE) AGCBBCFA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Toshiba</b>	<b>SLC</b>	8Gx8bit	TH58TEG6H2HBA4C (CEx2) TH58TEG6H2HBAMC (CEx2)	8K/24nm/ Toggle 2.0	8GB	(2CH/1CE) FGCBBABA.bin	1
					16GB	(4CH/1CE) FGCBBADA.bin	2
					32GB	(4CH/2CE) FGCBBABA.bin	4
					64GB	(4CH/4CE) FGCBBABA.bin	8
		16Gx8bit	TH58TEG7H2HBA8C (CEx4) TH58TEG7H2HBASC (CEx4)	8K/24nm/ Toggle 2.0	16GB	(2CH/2CE) FGCBBABA.bin	1
					32GB	(4CH/2CE) FGCBBABA.bin	2
					64GB	(4CH/4CE) FGCBBABA.bin	4
		32Gx8bit	TH58TEG8H2HBA89 (CEx4) TH58TEG8H2HBAS9 (CEx4)	8K/24nm/ Toggle 2.0 (multi-LUN)	32GB	(2CH/2CE) FGCBBABA.bin	1
					64GB	(4CH/2CE) FGCBBABA.bin	2

**NOTE:**

1. For other special CH/CE configuration requirements such as 3CH/2CE and 3CH/4CE, please contact with our FAE members to get further support.
2. For Toshiba older generation 24nm/32nm NAND Flash, please send its Datasheet to our FAE members first and then we will ask our FW engineer to estimate whether the JMF608/JMF609 can support it or not.
3. For Samsung 21nm NAND Flash, please send its Datasheet to our FAE members first and then we will ask our FW engineer to estimate whether the JMF608/JMF609 can support it or not.

### 3.2 Intel NAND Flash

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	8Gx8bit	JS29F64G08ACMF3 (CEx1)	8K/20nm L84A/ ONFi 2.3	8GB	(1CH/1CE) BDCCBAAA.bin	1
					16GB	(2CH/1CE) BDCCBABA.bin	2
					24GB	(3CH/1CE) BDCCBACA.bin	3
					32GB	(4CH/1CE) BDCCBADA.bin	4
					64GB	(4CH/2CE) BDCCBAHA.bin	8
		16Gx8bit	JS29F16B08CCMF2 (CEx2) JS29F16B08CCMF3 (CEx2)	8K/20nm L84A/ ONFi 2.3	16GB	(1CH/2CE) BDCCBAEA.bin	1
					32GB	(2CH/2CE) BDCCBAFA.bin	2
					64GB	(4CH/2CE) BDCCBAHA.bin	4
					128GB	(4CH/4CE) BDCCBAPA.bin	8
		32Gx8bit	JS29F32B08JCMF3 (CEx4)	8K/20nm L84A/ ONFi 2.3	32GB	(1CH/4CE) BDCCBAMA.bin	1
					64GB	(2CH/4CE) BDCCBANA.bin	2
					128GB	(4CH/4CE) BDCCBAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	8Gx8bit	PF29F64G08LCMFS (CEx1)	16K/20nm L84C/ ONFi 3.0	8GB	(1CH/1CE) CDADCAAA.bin	1
					16GB	(2CH/1CE) CDADCABA.bin	2
					24GB	(3CH/1CE) CDADCACA.bin	3
					32GB	(4CH/1CE) CDADCADA.bin	4
					64GB	(4CH/2CE) CDADCAHA.bin	8
		16Gx8bit	PF29F16B08MCMFS (CEx2)	16K/20nm L84C/ ONFi 3.0	16GB	(2CH/1CE) CDADCABA.bin	1
					32GB	(4CH/1CE) CDADCADA.bin	2
					64GB	(4CH/2CE) CDADCAHA.bin	4
					128GB	(4CH/4CE) CDADCAPA.bin	8
		32Gx8bit	PF29F32B08NCMFS (CEx4)	16K/20nm L84C/ ONFi 3.0	32GB	(2CH/2CE) CDADCAFA.bin	1
					64GB	(4CH/2CE) CDADCAHA.bin	2
					128GB	(4CH/4CE) CDADCAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	16Gx8bit	PF29F16B08LCMF3 (CEx1)	16K/20nm L85A/ ONFi 2.3	16GB	(1CH/1CE) BDBDCAAA.bin	1
					32GB	(2CH/1CE) BDBDCABA.bin	2
					48GB	(3CH/1CE) BDBDCACA.bin	3
					64GB	(4CH/1CE) BDBDCADA.bin	4
					128GB	(4CH/2CE) BDBDCAHA.bin	8
		32Gx8bit	PF29F32B08MCMF3 (CEx2)	16K/20nm L85A/ ONFi 2.3	32GB	(2CH/1CE) BDBDCABA.bin	1
					64GB	(4CH/1CE) BDBDCADA.bin	2
					128GB	(4CH/2CE) BDBDCAHA.bin	4
					256GB	(4CH/4CE) BDBDCAPA.bin	8
		64Gx8bit	PF29F64B08NCMF3 (CEx4)	16K/20nm L85A/ ONFi 2.3	64GB	(2CH/2CE) BDBDCAFA.bin	1
					128GB	(4CH/2CE) BDBDCAHA.bin	2
					256GB	(4CH/4CE) BDBDCAPA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	32Gx8bit	PF29F32B08MCMF2 (CEx2)	16K/20nm L85A/ ONFi 3.0	32GB	(2CH/1CE) CDBDCABA.bin	1
					64GB	(4CH/1CE) CDBDCADA.bin	2
					128GB	(4CH/2CE) CDBDCAHA.bin	4
					256GB	(4CH/4CE) CDBDCAPA.bin	8
		64Gx8bit	PF29F64B08NCMF2 (CEx4)	16K/20nm L85A/ ONFi 3.0	64GB	(2CH/2CE) CDBDCAFA.bin	1
					128GB	(4CH/2CE) CDBDCAHA.bin	2
					256GB	(4CH/4CE) CDBDCAPA.bin	4
		128Gx8bit	PF29F01T08OCMF2 (CEx8)	16K/20nm L85A/ ONFi 3.0	128GB	(2CH/4CE) CDBDCANA.bin	1
					256GB	(4CH/4CE) CDBDCAPA.bin	2

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	16Gx8bit	PF29F16B08LCMFS (CEx1)	16K/20nm L85C/ ONFi 3.0	16GB	(1CH/1CE) CDBDCAAA.bin	1
					32GB	(2CH/1CE) CDBDCABA.bin	2
					48GB	(3CH/1CE) CDBDCACA.bin	3
					64GB	(4CH/1CE) CDBDCADA.bin	4
					128GB	(4CH/2CE) CDBDCAHA.bin	8
		32Gx8bit	PF29F32B08MCMFS (CEx2)	16K/20nm L85C/ ONFi 3.0	32GB	(2CH/1CE) CDBDCABA.bin	1
					64GB	(4CH/1CE) CDBDCADA.bin	2
					128GB	(4CH/2CE) CDBDCAHA.bin	4
					256GB	(4CH/4CE) CDBDCAPA.bin	8
		64Gx8bit	PF29F64B08NCMFS (CEx4)	16K/20nm L85C/ ONFi 3.0	64GB	(2CH/2CE) CDBDCAFA.bin	1
					128GB	(4CH/2CE) CDBDCAHA.bin	2
					256GB	(4CH/4CE) CDBDCAPA.bin	4
		128Gx8bit	PF29F01T08OCMFS (CEx8)	16K/20nm L85C/ ONFi 3.0	128GB	(2CH/4CE) CDBDCANA.bin	1
					256GB	(4CH/4CE) CDBDCAPA.bin	2

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	8Gx8bit	JS29F64G08ACME2 (CEx1)	8K/25nm L74A/ ONFi 2.2	8GB	(1CH/1CE) BDCCBAAA.bin	1
					16GB	(2CH/1CE) BDCCBABA.bin	2
					24GB	(3CH/1CE) BDCCBACA.bin	3
					32GB	(4CH/1CE) BDCCBADA.bin	4
					64GB	(4CH/2CE) BDCCBAHA.bin	8
		16Gx8bit	JS29F16B08CCME2 (CEx2)	8K/25nm L74A/ ONFi 2.2	16GB	(1CH/2CE) BDCCBAEA.bin	1
					32GB	(2CH/2CE) BDCCBAFA.bin	2
					64GB	(4CH/2CE) BDCCBAHA.bin	4
					128GB	(4CH/4CE) BDCCBAPA.bin	8
		32Gx8bit	JS29F32B08JCME2 (CEx4)	8K/25nm L74A/ ONFi 2.2	32GB	(1CH/4CE) BDCCBAMA.bin	1
					64GB	(2CH/4CE) BDCCBANA.bin	2
					128GB	(4CH/4CE) BDCCBAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	8Gx8bit	JS29F64G08ACME3 (CEx1)	8K/25nm L74A/ ONFi 2.2	8GB	(1CH/1CE) ADCCBAAA.bin	1
					16GB	(2CH/1CE) ADCCBABA.bin	2
					24GB	(3CH/1CE) ADCCBACA.bin	3
					32GB	(4CH/1CE) ADSCBADA.bin	4
					64GB	(4CH/2CE) ADCCBAHA.bin	8
		16Gx8bit	JS29F16B08CCME3 (CEx2)	8K/25nm L74A/ ONFi 2.2	16GB	(1CH/2CE) ADCCBAEA.bin	1
					32GB	(2CH/2CE) ADCCBAFA.bin	2
					64GB	(4CH/2CE) ADCCBAHA.bin	4
					128GB	(4CH/4CE) ADCCBAPA.bin	8
		32Gx8bit	JS29F32B08JCME3 (CEx4)	8K/25nm L74A/ ONFi 2.2	32GB	(1CH/4CE) ADCCBAMA.bin	1
					64GB	(2CH/4CE) ADCCBANA.bin	2
					128GB	(4CH/4CE) ADCCBAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	16Gx8bit	PF29F16B16MCME1 (CEx2)	8K/25nm L74A/ ONFi 2.2	16GB	(2CH/1CE) BDCCBABA.bin	1
					32GB	(4CH/1CE) BDCCBADA.bin	2
					64GB	(4CH/2CE) BDCCBAHA.bin	4
					128GB	(4CH/4CE) BDCCBAPA.bin	8
		32Gx8bit	PF29F32B16NCME1 (CEx4)	8K/25nm L74A/ ONFi 2.2	32GB	(2CH/2CE) BDCCBAFA.bin	1
					64GB	(4CH/2CE) BDCCBAHA.bin	2
					128GB	(4CH/4CE) BDCCBAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>MLC</b>	64Gx8bit	JS29F64B08OCME1 (CEx4)	8K/25nm L74A/ ONFi 2.2 (multi-LUN)	64GB	(2CH/2CE) BDCCBBFA.bin	1
					128GB	(4CH/2CE) BDCCBBHA.bin	2

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Intel</b>	<b>SLC</b>	8Gx8bit	JS29F64G08CCNE1 (CEx2)	8K/25nm L74A/ ONFi 2.2	8GB	(1CH/2CE) BHCBBAEA.bin	1
					16GB	(2CH/2CE) BHCBBafa.bin	2
					32GB	(4CH/2E) BHCBBaHA.bin	4
					64GB	(4CH/4CE) BHCBBaPA.bin	8

**NOTE:**

1. For other special CH/CE configuration requirements such as 3CH/2C and 3CH/4CE, please contact with our FAE members to get further support.
2. For Intel older generation 25nm/34nm NAND Flash, please send its Datasheet to our FAE members first and then we will ask our FW engineer to estimate whether the JMF608/JMF609 can support it or not.
3. For Samsung 21nm NAND Flash, please send its Datasheet to our FAE members first and then we will ask our FW engineer to estimate whether the JMF608/JMF609 can support it or not.

### 3.3 Micron NAND Flash

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	8Gx8bit	MT29F64G08CBABB (CEx1)	8K/20nm L84A/ ONFi 2.3	8GB	(1CH/1CE) BDCCBAAA.bin	1
					16GB	(2CH/1CE) BDCCBABA.bin	2
					24GB	(3CH/1CE) BDCCBACA.bin	3
					32GB	(4CH/1CE) BDCCBADA.bin	4
					64GB	(4CH/2CE) BDCCBAHA.bin	8
		16Gx8bit	MT29F128G08CFABB (CEx2)	8K/20nm L84A/ ONFi 2.3	16GB	(1CH/2CE) BDCCBAEA.bin	1
					32GB	(2CH/2CE) BDCCBAFA.bin	2
					64GB	(4CH/2CE) BDCCBAHA.bin	4
					128GB	(4CH/4CE) BDCCBAPA.bin	8

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	8Gx8bit	MT29F64G08CBCBB (CEx1)	8K/20nm L84A/ ONFi 2.3	8GB (1CH/1CE) BDCCBAAA.bin	1
					16GB (2CH/1CE) BDCCBABA.bin	2
					24GB (3CH/1CE) BDCCBACA.bin	3
					32GB (4CH/1CE) BDCCBADA.bin	4
					64GB (4CH/2CE) BDCCBAHA.bin	8
	16Gx8bit		MT29F128G08CECBB (CEx2)	8K/20nm L84A/ ONFi 2.3	16GB (1CH/2CE) BDCCBAEA.bin	1
					32GB (2CH/2CE) BDCCBAFA.bin	2
					64GB (4CH/2CE) BDCCBAHA.bin	4
					128GB (4CH/4CE) BDCCBAPA.bin	8
	32Gx8bit		MT29F256G08CMCBB (CEx4)	8K/20nm L84A/ ONFi 2.3	32GB (1CH/4CE) BDCCBAMA.bin	1
					64GB (2CH/4CE) BDCCBANA.bin	2
					128GB (4CH/4CE) BDCCBAPA.bin	4

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	8Gx8bit	16K/20nm L84C/ ONFi 3.0	8GB	(1CH/1CE) CDADCAAA.bin	1
				16GB	(2CH/1CE) CDADCABA.bin	2
				24GB	(3CH/1CE) CDADCACA.bin	3
				32GB	(4CH/1CE) CDADCADA.bin	4
				64GB	(4CH/2CE) CDADCAHA.bin	8
		16Gx8bit	16K/20nm L84C/ ONFi 3.0	16GB	(2CH/1CE) CDADCABA.bin	1
				32GB	(4CH/1CE) CDADCADA.bin	2
				64GB	(4CH/2CE) CDADCAHA.bin	4
				128GB	(4CH/4CE) CDADCAPA.bin	8
		32Gx8bit	16K/20nm L84C/ ONFi 3.0	32GB	(2CH/2CE) CDADCAFA.bin	1
				64GB	(4CH/2CE) CDADCAHA.bin	2
				128GB	(4CH/4CE) CDADCAPA.bin	4

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	16Gx8bit	16K/20nm L85A/ ONFi 3.0	16GB	(1CH/1CE) CDBDCAAA.bin	1
				32GB	(2CH/1CE) CDBDCABA.bin	2
				48GB	(3CH/1CE) CDBDCACA.bin	3
				64GB	(4CH/1CE) CDBDCADA.bin	4
				128GB	(4CH/2CE) CDBDCAHA.bin	8
		32Gx8bit	16K/20nm L85A/ ONFi 3.0	32GB	(2CH/1CE) CDBDCABA.bin	1
				64GB	(4CH/1CE) CDBDCADA.bin	2
				128GB	(4CH/2CE) CDBDCAHA.bin	4
				256GB	(4CH/4CE) CDBDCAPA.bin	8
		64Gx8bit	16K/20nm L85A/ ONFi 3.0	64GB	(2CH/2CE) CDBDCAFA.bin	1
				128GB	(4CH/2CE) CDBDCAHA.bin	2
				256GB	(4CH/4CE) CDBDCAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	64Gx8bit	MT29F512G08CKCAB (CEx2)	16K/20nm L85A/ ONFi 3.0 (multi-LUN)	64GB	(2CH/1CE) CDBDCBBA.bin	1
					128GB	(4CH/1CE) CDBDCBDA.bin	2
					256GB	(4CH/2CE) CDBDCBHA.bin	4
		128Gx8bit	MT29F1TG08CUCAB (CEx4)	16K/20nm L85A/ ONFi 3.0 (multi-LUN)	128GB	(2CH/2CE) CDBDCBFA.bin	1
					256GB	(4CH/2CE) CDBDCBHA.bin	2

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	16Gx8bit	16K/20nm L85C/ ONFi 3.0	16GB	(1CH/1CE) CDBDCAAA.bin	1
				32GB	(2CH/1CE) CDBDCABA.bin	2
				48GB	(3CH/1CE) CDBDCACA.bin	3
				64GB	(4CH/1CE) CDBDCADA.bin	4
				128GB	(4CH/2CE) CDBDCAHA.bin	8
		32Gx8bit	16K/20nm L85C/ ONFi 3.0	32GB	(2CH/1CE) CDBDCABA.bin	1
				64GB	(4CH/1CE) CDBDCADA.bin	2
				128GB	(4CH/2CE) CDBDCAHA.bin	4
				256GB	(4CH/4CE) CDBDCAPA.bin	8
		64Gx8bit	16K/20nm L85C/ ONFi 3.0	64GB	(2CH/2CE) CDBDCAFA.bin	1
				128GB	(4CH/2CE) CDBDCAHA.bin	2
				256GB	(4CH/4CE) CDBDCAPA.bin	4

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	16Gx8bit	MT29F128G08CBEBB (CEx1)	16K/20nm L85C/ ONFi 3.0	16GB	(1CH/1CE) CDBDCAAA.bin	1
					32GB	(2CH/1CE) CDBDCABA.bin	2
					48GB	(3CH/1CE) CDBDCACA.bin	3
					64GB	(4CH/1CE) CDBDCADA.bin	4
					128GB	(4CH/2CE) CDBDCAHA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	8Gx8bit	MT29F64G08CBAAA (CEx1)	8K/25nm L74A/ Legacy	8GB	(1CH/1CE) ADCCBAAA.bin	1
					16GB	(2CH/1CE) ADCCBABA.bin	2
					24GB	(3CH/1CE) ADCCBACA.bin	3
					32GB	(4CH/1CE) ADSCBADA.bin	4
					64GB	(4CH/2CE) ADCCBAHA.bin	8
		16Gx8bit	MT29F128G08CFAAA (CEx2)	8K/25nm L74A/ Legacy	16GB	(1CH/2CE) ADCCBAEA.bin	1
					32GB	(2CH/2CE) ADCCBAFA.bin	2
					64GB	(4CH/2CE) ADCCBAHA.bin	4
					128GB	(4CH/4CE) ADCCBAPA.bin	8

Vendor	NAND Flash part number			Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	8Gx8bit	MT29F64G08CBAAB (CEx1)	8K/25nm L74A/ ONFi 2.2	8GB	(1CH/1CE) BDCCBAAA.bin	1
					16GB	(2CH/1CE) BDCCBABA.bin	2
					24GB	(3CH/1CE) BDCCBACA.bin	3
					32GB	(4CH/1CE) BDCCBADA.bin	4
					64GB	(4CH/2CE) BDCCBAHA.bin	8
		16Gx8bit	MT29F128G08CFAAB (CEx2)	8K/25nm L74A/ ONFi 2.2	16GB	(1CH/2CE) BDCCBAEA.bin	1
					32GB	(2CH/2CE) BDCCBAFA.bin	2
					64GB	(4CH/2CE) BDCCBAHA.bin	4
					128GB	(4CH/4CE) BDCCBAPA.bin	8

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	4Gx8bit	MT29F32G08CBADA (CEx1)	8K/20nm L83A/ Legacy	4GB (1CH/1CE) ADBCBAAA.bin	1
					8GB (2CH/1CE) ADBCBABA.bin	2
					12GB (3CH/1CE) ADBCBACA.bin	3
					16GB (4CH/1CE) ADBCBADA.bin	4
					32GB (4CH/2CE) ADBCBAHA.bin	8
		8Gx8bit	MT29F64G08CFADA (CEx2)	8K/20nm L83A/ Legacy	8GB (1CH/2CE) ADBCBAEA.bin	1
					16GB (2CH/2CE) ADBCBAFA.bin	2
					32GB (4CH/2CE) ADBCBAHA.bin	4
					64GB (4CH/4CE) ADBCBAHA.bin	8

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>MLC</b>	4Gx8bit	MT29F32G08CBADB (CEx1)	8K/20nm L83A/ ONFi 2.3	4GB (1CH/1CE) BDBCBAAB.bin	1
					8GB (2CH/1CE) BDBCBAAB.bin	2
					12GB (3CH/1CE) BDBCBAAB.bin	3
					16GB (4CH/1CE) BDBCBAAB.bin	4
					32GB (4CH/2CE) BDBCBAAB.bin	8
		8Gx8bit	MT29F64G08CFADB (CEx2)	8K/20nm L83A/ ONFi 2.3	8GB (1CH/2CE) BDBCBAEA.bin	1
					16GB (2CH/2CE) BDBCBAFA.bin	2
					32GB (4CH/2CE) BDBCBAHA.bin	4
					64GB (4CH/4CE) BDBCBAHA.bin	8

Vendor	NAND Flash part number		Process	Cap.	Bin name	ea
<b>Micron</b>	<b>SLC</b>	8Gx8bit	16K/20nm M84A/ ONFi 3.0	8GB	(1CH/1CE) CHBCCAAA.bin	1
				16GB	(2CH/1CE) CHBCCABA.bin	2
				24GB	(3CH/1CE) CHBCCACA.bin	3
				32GB	(4CH/1CE) CHBCCADA.bin	4
				64GB	(4CH/2CE) CHBCCAHA.bin	8
		16Gx8bit	16K/20nm M84A/ ONFi 3.0	16GB	(2CH/1CE) CHBCCABA.bin	1
				32GB	(4CH/1CE) CHBCCADA.bin	2
				64GB	(4CH/2CE) CHBCCAHA.bin	4
				128GB	(4CH/4CE) CHBCCAPA.bin	8
		32Gx8bit	16K/20nm M84A/ ONFi 3.0	32GB	(2CH/2CE) CHBCCAFA.bin	1
				64GB	(4CH/2CE) CHBCCAHA.bin	2
				128GB	(4CH/4CE) CHBCCAPA.bin	4

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# **JMicron**

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***Serial Link the World***